

FIG. 1A

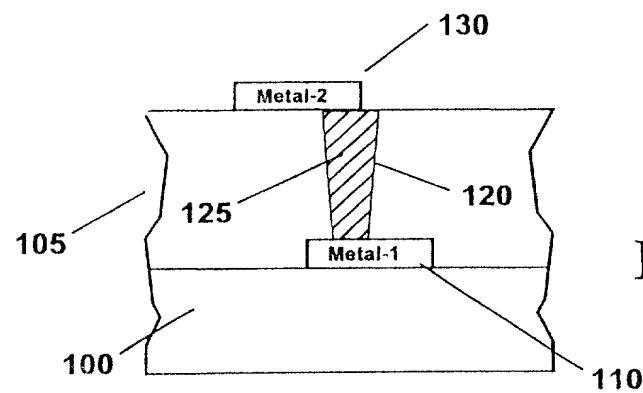


FIG. 1B

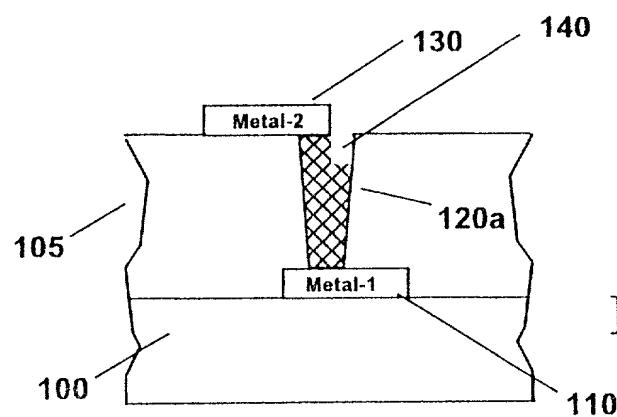


FIG. 1C

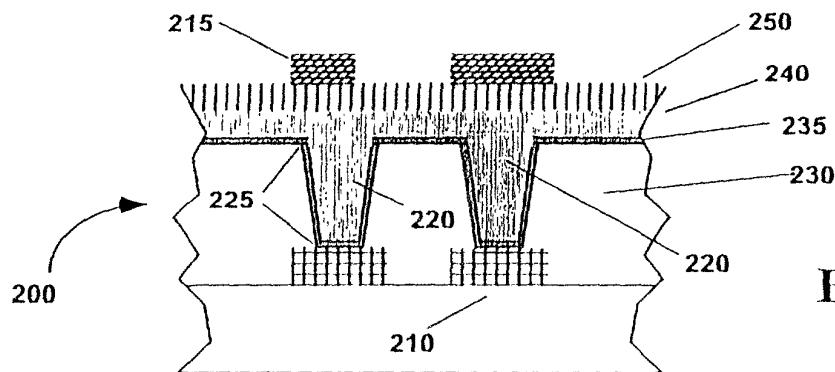


FIG. 2A

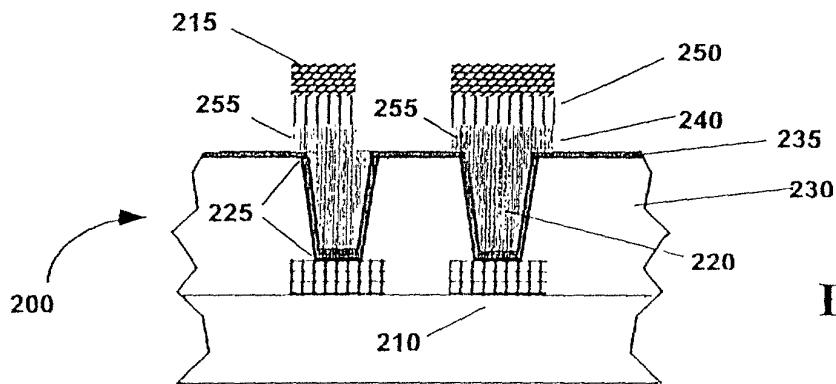


FIG. 2B

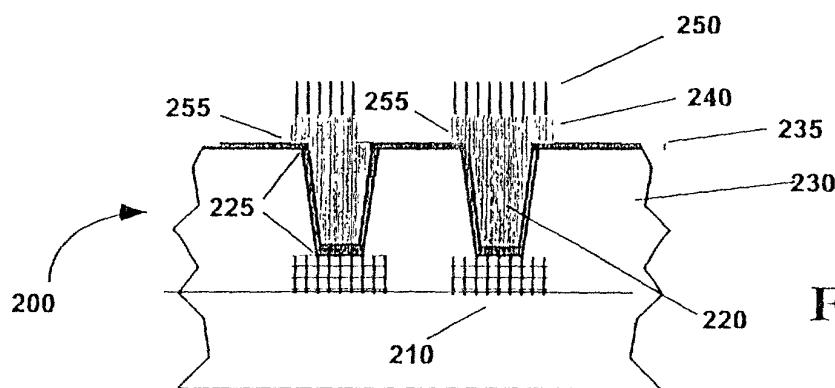


FIG. 2C

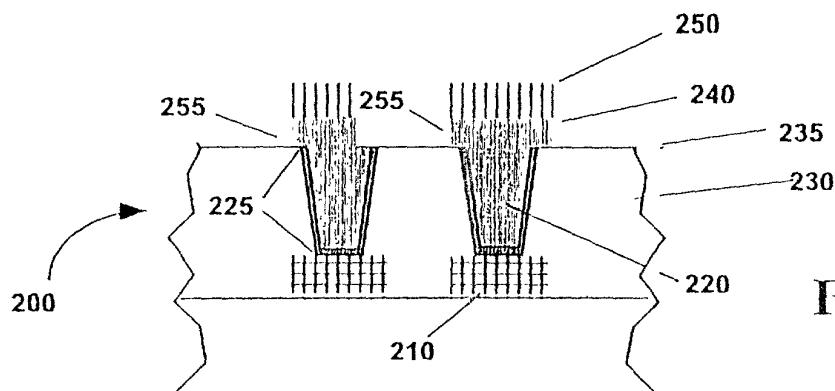


FIG. 2D

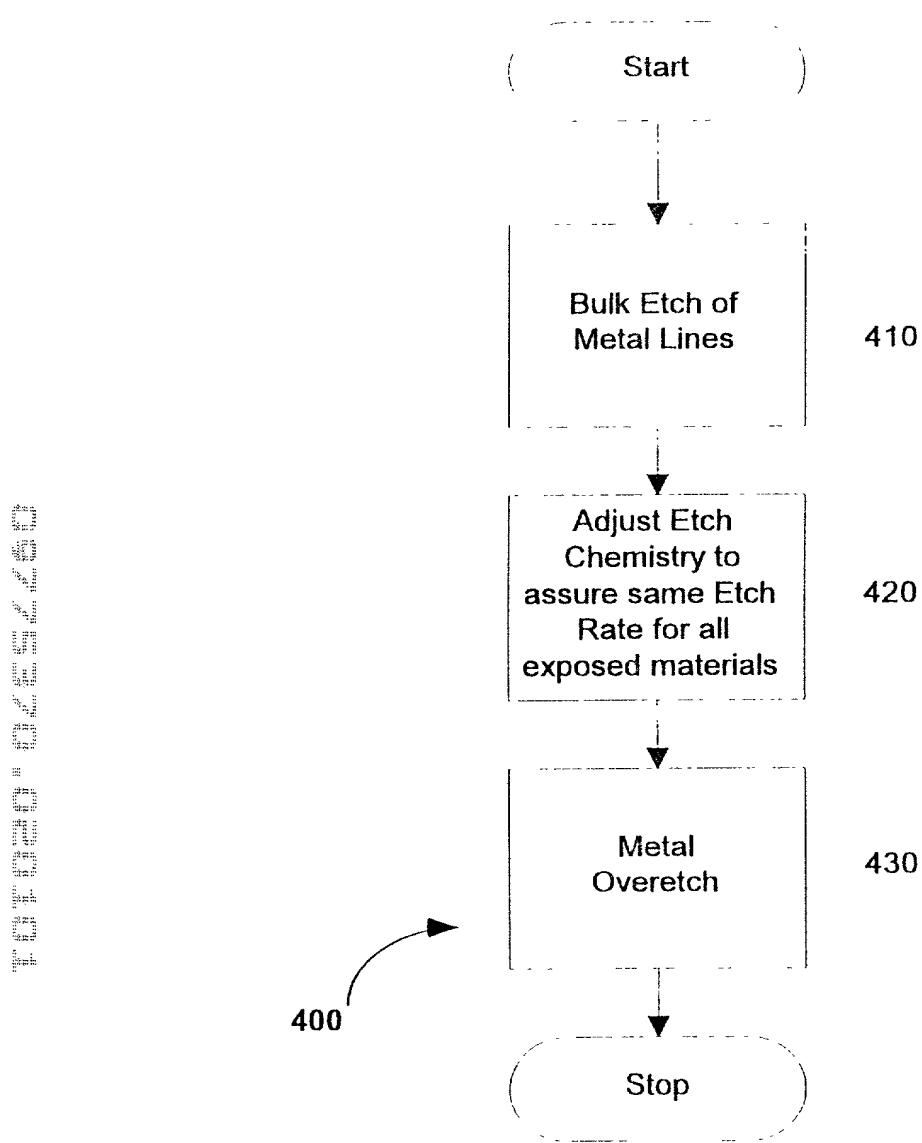


FIG. 3

FIG. 4

	TiN +	AlCu	Copper	Ti +				
Main etch chamber	AlCu Bulk	Endpoint	Residue	1:1:1 Overetch				
	Step 01	Step 02	Step 03	Step 04	Step 05	Step 06	Step 07	Step 08
Pressure (mT)	0.00	10.00	10.00	10.00	10.00	10.00	10.00	0.00
RF-Top (W)	0	0	360	360	360	360	360	0
RF-Bottom (W)	0	0	100	225	225	100	100	0
Gap (cm)	N/A							
BCl3 (sccm)	40.0	40.0	40.0	40.0	50.0	50.0	0.0	0.0
Cl2 (sccm)	40.0	40.0	40.0	40.0	30.0	30.0	0.0	0.0
SF6 (sccm)	0.0	0.0	0.0	0.0	0.0	20.0	0.0	0.0
Die clamp (")	0.0	10.0	10.0	10.0	10.0	10.0	0.0	0.0
Completion	Stab1	Time	EndPt	Time	Time	Time	Time	End
Time	30s	30s	24s	50s	5s	50s	10s	s
Channel			262 nm					
Delay (sec)			14					
Norm (sec)			2					
Norm value			0					
Trigger (%)			90					
Electrode Temp	50.0°C							
Chamber Temp	60.0°C							